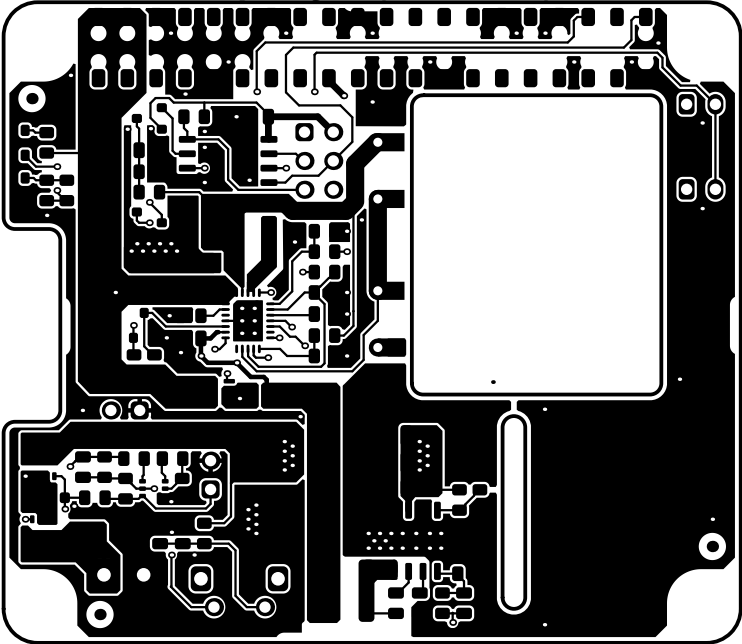
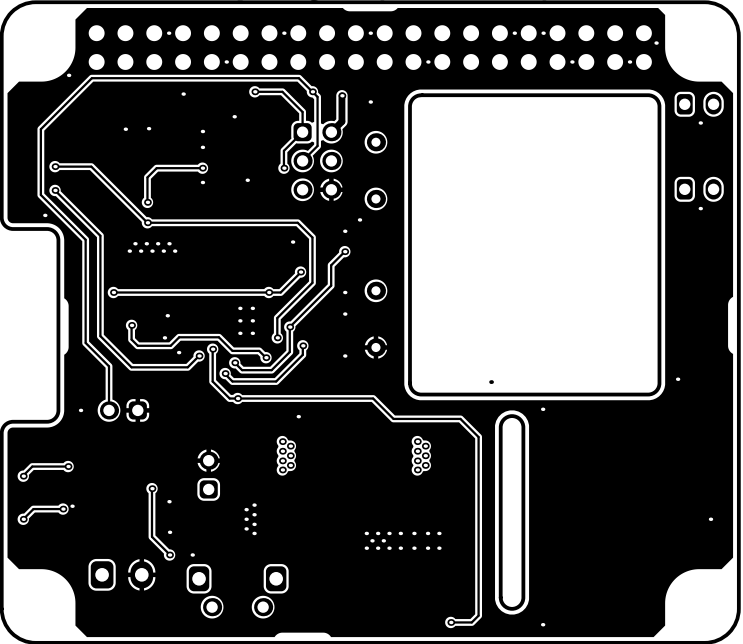


SCP-PI-B - Top Layer (Scale 3:2)



SCP-PI-B - Top Layer (Scale 3:2)



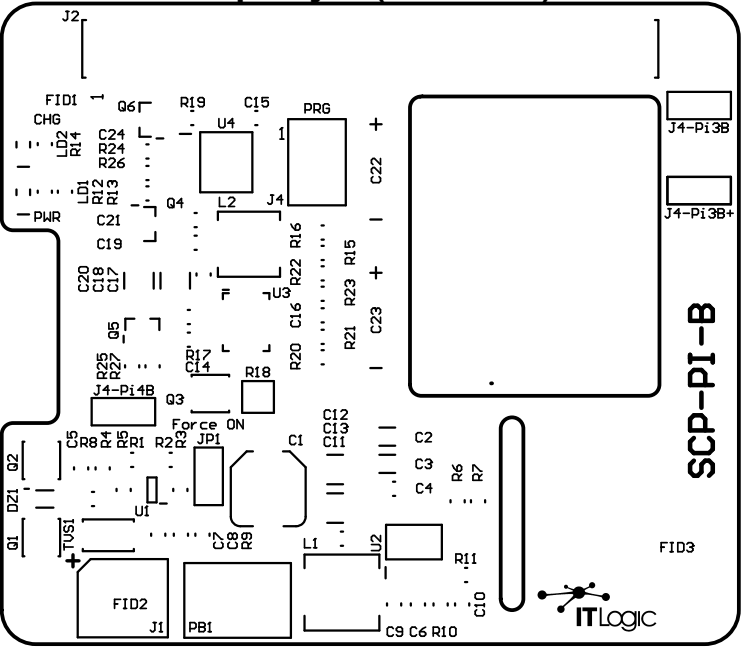
Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.0254mm	SM-001	Solder Mask	GTS
PbSn	Top Surface Finish	0.0200mm		Surface Finish	
CF-004	Top Layer	0.0350mm		Signal	GTL
Prepreg		0.1067mm	PP-014	Dielectric	
CF-004	Int1 (GND)	0.0175mm		Internal Plane	GP1
Core		1.2650mm	Core-039	Dielectric	
CF-004	Int2 (GND)	0.0175mm		Internal Plane	GP2
Prepreg		0.1067mm	PP-014	Dielectric	
CF-004	Bottom Layer	0.0350mm		Signal	GBL
PbSn	Bottom Surface Finish	0.0200mm		Surface Finish	
Surface Material	Bottom Solder	0.0254mm	SM-001	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.6741mm					

Board Specification

Minimum Track	0.2 mm	Solder Mask Color	Blue
Minimum Gap	0.2 mm	Silkscreen	White
VIA Process	Tented	Board Finish	HASL - LEAD

SCP-PI-B - Top Layer (Scale 3:2)



Project: **SuperCap UPS Rasp Pi**

Revision: **B**

Title: **Board Specifications**

Sheet: 1 of 2

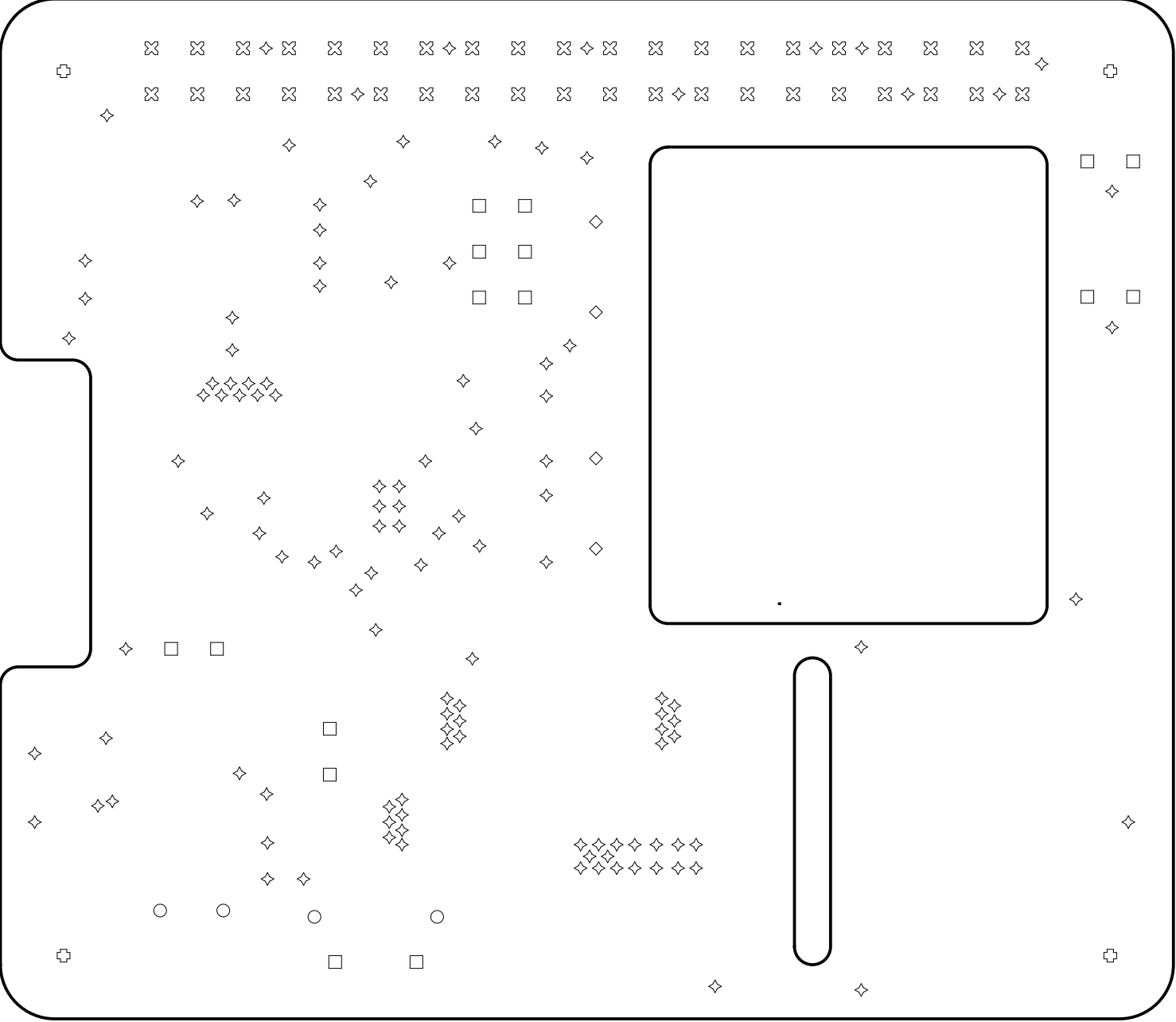
Author: **acortellini**

Date: **Nov-17-2019**

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SCP-PI-B - Drill Drawing View (Scale 3)



Drill Table

Symbol	Count	Hole Size	Plated	Hole Type	Via / Pad	Hole Tolerance
◇	124	0.30mm	Plated	Round	Via	None
◇	4	0.80mm	Plated	Round	Pad	None
□	16	1.00mm	Plated	Round	Pad	None
⊗	40	1.00mm	Non-Plated	Round	Pad	None
○	4	1.20mm	Plated	Round	Pad	None
⊕	4	2.75mm	Non-Plated	Round	Pad	None
	192 Total					